## IN THE CLAIMS

No amendments have been made to the claims.

Claims 1-5 (cancelled)

6. (previously presented) A method of forming copper interconnect, comprising: forming a barrier layer over a substrate having at least one trench therein; forming a copper seed layer on the surface of the barrier layer; forming a copper layer over the barrier and seed layers;

removing a portion of the copper layer by chemical mechanical polishing with a first slurry comprising a chelating organic acid buffer system, colloidal silica, and a low electrochemical oxidizer; and

removing at least a portion of the barrier layer by chemical mechanical polishing with a second slurry comprising a chelating organic acid buffer system, and colloidal silica; wherein the second slurry is formed without the oxidizer.

- 7. (original) The method of Claim 6, wherein the barrier layer comprises tantalum.
- 8. (original) The method of Claim 7, wherein the chelating organic acid buffer system comprises citric acid and potassium citrate.
- 9. (original) The method of Claim 8, wherein the oxidizer comprises hydrogen peroxide.
- 10. (original) The method of Claim 9, wherein the first slurry further comprises a corrosion inhibitor.
- 11. (original) The method of Claim 10, wherein the first slurry has a pH in the range of 3 to 6, and the corrosion inhibitor comprises benzotriazole.

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- 12. (withdrawn) A slurry produced by the process comprising:combining citric acid, potassium citrate, silica, hydrogen peroxide, and benzotriazole.
- 13. (withdrawn) The slurry produced by the process of Claim 12, wherein a concentration of citric acid is approximately 3g/l, a concentration of potassium citrate is approximately 3g/l, a concentration of silica is approximately 5 wt. %, a concentration of hydrogen peroxide is approximately 3 wt. %, and a concentration of benzotriazole is approximately 0.015 molar.
- 14. (withdrawn) The slurry produced by the process of Claim 13, further comprising combining the citric acid, potassium citrate, silica, hydrogen peroxide, and benzotriazole with water.
- 15. (withdrawn) A slurry, comprising:

  approximately 3 grams/liter of citric acid;

  approximately 3 grams/liter of potassium citrate;

  approximately 5 wt.% silica;

  approximately 3 wt.% hydrogen peroxide;

  approximately 0.015 molar benzotriazole; and
  the mixture and reaction products thereof.
- 16. (withdrawn) The slurry of Claim 15, wherein the slurry has a pH in the range of 3 to6.
- 17. (withdrawn) A slurry formed by the process of combining a organic acid, an organic acid salt; approximately 5 wt.% silica; approximately 3 wt.% hydrogen peroxide; and approximately 0.015 molar benzotriazole.

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- 18. (withdrawn) The slurry of Claim 17, wherein the organic acid comprises acetic acid.
- 19. (withdrawn) The slurry of Claim 18, wherein the organic acid salt comprises potassium acetate.
- 20. (withdrawn) The slurry of Claim 17, wherein the organic acid comprises 3 grams/liter of citric acid, and the organic acid salt comprises 3 grams/liter of potassium citrate.
- 21. (withdrawn) A slurry for polishing copper diffusion barriers, comprising: approximately 3 grams/liter of citric acid; approximately 3 grams/liter of potassium citrate; approximately 5 wt.% silica; approximately 0.015 molar benzotriazole; and the mixture and reaction products thereof.
- 22. (withdrawn) The slurry of Claim 21, wherein the copper diffusion barriers comprise tantalum.
- (withdrawn) The slurry of Claim 21, wherein the slurry has a pH in the range of 3 to
- 24. (withdrawn) A slurry for polishing barriers comprised of tantalum, comprising: organic acid, an organic acid salt, an abrasive, a corrosion inhibitor, and the mixture and reaction products thereof, and wherein no oxidizer is included.

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- 25. (withdrawn) The slurry of Claim 24, wherein the organic acid comprise citric acid.
- 26. (withdrawn) The slurry of Claim 24, wherein the corrosion inhibitor comprises benzotriazole, and wherein the slurry has a pH in the range of 3 to 6.
- 27. (withdrawn) The slurry of Claim 25, wherein the organic acid salt comprises potassium citrate.